WHAT IS CLAIMED IS:

1. A circuit board comprising a base member, an interconnect layer formed on a part of the base member, an electrically-floating conductive layer formed on a substantially remaining part of the base member and having an edge adjacent to an edge of the interconnect layer, and a dielectric layer covering a part of the interconnect layer and an entire surface of the electrically-floating conductive layer and filling a gap between the edge of the interconnect layer and the edge of the electrically-floating conductive layer.

2. The circuit board as defined in claim 1, wherein a pair of the interconnect layers are disposed on each of both surfaces of the base member.

3. The circuit board as defined in claim 2, wherein volumes of the pair of the interconnect layers are substantially same.

4. The circuit board as defined in claim 1, wherein the interconnect layer includes patterns having a larger width.

5. A circuit board comprising a base member, an first interconnect layer formed on a part of the base member, an electrically-floating conductive layer formed on a substantially remaining part of the base member and having an edge adjacent to an edge of the first interconnect layer, and a dielectric layer covering a part of the first interconnect layer and an entire surface of the electrically-floating conductive layer and filling a gap between the edge of the first interconnect layer and the edge of the electrically-floating conductive layer, and a second interconnect layer formed on the dielectric layer.

6. The circuit board as defined in claim 5, wherein the interconnect layer includes patterns having a larger width.

7. A circuit board comprising a base member, an interconnect layer formed on a part of the base member, an electrically-floating conductive layer formed on a substantially remaining part of the base member and having an edge adjacent to an edge of the interconnect layer, a dielectric layer covering a part of the interconnect layer and an entire surface of the electrically-floating conductive layer and filling a gap between the edge of the

interconnect layer and the edge of the electrically-floating conductive layer, and a die disposed on the dielectric layer.

8. The circuit board as defined in claim 7, wherein the interconnect layer includes patterns having a larger width.